MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

NOTES:

ON Semiconductor®



CERAMIC DIP 34, 50.8x50.8 CASE 125BL ISSUE O

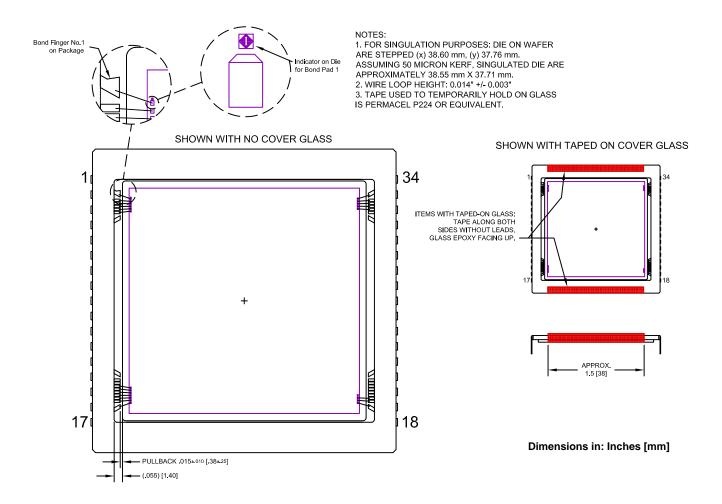
DATE 03 JUL 2014

1. Die is visually aligned within 1 degree of any package cavity edge. SHOWN WITH SEALED COVER GLASS 2. Die surface flatness: 0.002" Max T.I.R. - HEAT SINK .040±.002 [1.02±.05] - CERAMIC .065±.007 [1.65±.18] GLASS .030±.003 [.76±.08] - SQ. 1.900±.003 [48.26±.08] -- .180±.010 [4.57±.25] SQ. 1.519±.010 [38.58±.25] --010±010 [25±25] CERAMIC 2.000±020 SQ [50.80±51] PIN LD. ПЪ 34 Ę Brazed Area 100 [2.54] TYP. PITCH MARKING CODE 1 600±005 -[40 64±13] 050 [1.27] 018±003 [46±08] TYP 17 18 Top of Die to tTop of Glass 068±010 [1 73±25] - HEAT SINK 1.800±.003 SQ [45.72±.08] -Top of Die to Top of Ceramlc 036±010 [.91±25] Bottom of Package - to Top of Die 069±005 [1 76±13] [**/**] 0.002"] mm An 2.010±.020 [51.05±.51] .010^{+.002}_.001 [.25^{+.05}_.03] Dimensions in: Inches [mm]

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